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PO BOX 655474, M/S 3999
DALLAS, TX 75265

05/17/2006 HDEMESS2 00000089 200668 10797779

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Karen Vertz	(Depositor's name)
Karen Vertz Karen Vertz	(Signature)
May 17, 2006	(Date)

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/797,779	03/09/04	Kejun Zeng	TI-36626	4149

TITLE OF INVENTION: METHOD OF SEMICONDUCTOR DEVICE ASSEMBLY INCLUDING FATIGUE-RESISTANT TERNARY SOLDER ALLOY

APPLN. TYPE	SMALL ENTITY	ISSUE FEE	PUBLICATION FEE	TOTAL FEE(S) DUE	DATE DUE
nonprovisional	NO	\$1,400	\$300	\$1,700	07/24/2006

EXAMINER	ART UNIT	CLASS-SUBCLASS
EDMONDSON, LYNNE RENEE	1725	228-248100

1. Change of correspondence address or indication of "Fee Address" (37 CFR 1.363).

- ☐ Change of correspondence address (or Change of Correspondence Address form PTO/SB/122) attached.
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- (1) the names of up to 3 registered patent attorneys or agents OR, alternatively,
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1	W. James Brady, III
2	Frederick J. Telecky, Jr.
3	

3. ASSIGNEE NAME AND RESIDENCE DATA TO BE PRINTED ON THE PATENT (print or type)

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PO BOX 655474, M/S 3999
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☐ a. Applicant claims SMALL ENTITY status. See 37 CFR 1.27.☐ b. Applicant is no longer claiming SMALL ENTITY status. See 37 CFR 1.27(g)(2).

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Authorized Signature

Date

15 May 2006

Typed or printed name

Gary C. Honeycutt

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20,250

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Kejun Zeng

Docket Number: TI-36626

Serial No.: 10/797,779

Art Unit: 1725

Filed: 03/09/04

Examiner: Lynne R. Edmondson

For: Method of Semiconductor Device Assembly Including
Fatigue-Resistant Ternary Solder Alloy

CERTIFICATION OF FACSIMILE TRANSMISSION	
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<u>Karen Vertz</u> Karen Vertz	<u>5-17-06</u> Date

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<input type="checkbox"/> DIVISIONAL APP'N		
NAME OF INVENTOR(S): Kejun Zeng		RECEIPT DATE & SERIAL NO.: Serial No.: 10/797,779 Filing Date: 03/09/04
TITLE OF INVENTION: Method of Semiconductor Device Assembly Including Fatigue-Resistant Ternary Solder Alloy		
TI FILE NO.: TI-36626	DEPOSIT ACCT. NO.: 20-0668	
FAXED: 5-17-06 DUE: 7-24-06 ATTY/SECY: GCH/kjv		

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